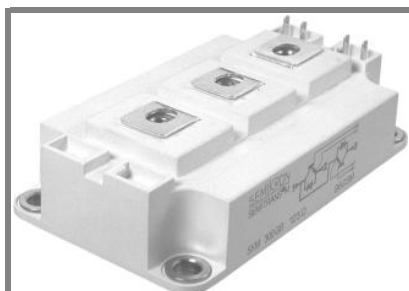


# SKM 150GB128D



**SEMITRANS® 3**

## SPT IGBT Modules

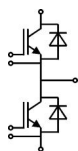
### SKM 150GB128D

#### Features

- SPT = Soft punch-through technology
- $V_{CEsat}$  with positive temperature coefficient
- High short circuit capability, self limiting to  $6 \times I_C$

#### Typical Applications

- AC inverter drives
- UPS
- Electronic welders at  $f_{sw}$  up to 20 kHz

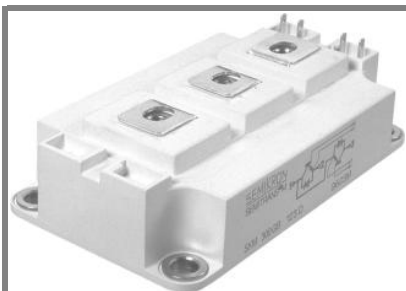


**GB**

Absolute Maximum Ratings			T <sub>c</sub> = 25 °C, unless otherwise specified	
Symbol	Conditions		Values	Units
IGBT				
V <sub>CES</sub>	T <sub>j</sub> = 25 °C		1200	V
I <sub>C</sub>	T <sub>j</sub> = 150 °C	T <sub>c</sub> = 25 °C	200	A
		T <sub>c</sub> = 80 °C	140	A
I <sub>CRM</sub>	I <sub>CRM</sub> = 2xI <sub>Cnom</sub>		200	A
V <sub>GES</sub>			± 20	V
t <sub>psc</sub>	V <sub>CC</sub> = 600 V; V <sub>GE</sub> ≤ 20 V; T <sub>j</sub> = 125 °C V <sub>CES</sub> < 1200 V		10	µs
Inverse Diode				
I <sub>F</sub>	T <sub>j</sub> = 150 °C	T <sub>case</sub> = 25 °C	150	A
		T <sub>case</sub> = 80 °C	100	A
I <sub>FRM</sub>	I <sub>FRM</sub> = 2xI <sub>Fnom</sub>		200	A
I <sub>FSM</sub>	t <sub>p</sub> = 10 ms; sin.	T <sub>j</sub> = 150 °C	1100	A
Module				
I <sub>t(RMS)</sub>			500	A
T <sub>vj</sub>			- 40... + 150	°C
T <sub>stg</sub>			- 40... + 125	°C
V <sub>isol</sub>	AC, 1 min.		4000	V

Characteristics			T <sub>c</sub> = 25 °C, unless otherwise specified			
Symbol	Conditions		min.	typ.	max.	Units
IGBT						
V <sub>GE(th)</sub>	V <sub>GE</sub> = V <sub>CE</sub> , I <sub>C</sub> = 4 mA		4,5	5,5	6,5	V
I <sub>CES</sub>	V <sub>GE</sub> = 0 V, V <sub>CE</sub> = V <sub>CES</sub> T <sub>j</sub> = 25 °C			0,2	0,6	mA
V <sub>CE0</sub>			T <sub>j</sub> = 25 °C		1	1,15
			T <sub>j</sub> = 125 °C		0,9	1,05
r <sub>CE</sub>	V <sub>GE</sub> = 15 V		T <sub>j</sub> = 25 °C		9	12
			T <sub>j</sub> = 125 °C		12	15
V <sub>CE(sat)</sub>	I <sub>Cnom</sub> = 100 A, V <sub>GE</sub> = 15 V		T <sub>j</sub> = 25 °C <sub>chiplev.</sub>		1,9	2,35
			T <sub>j</sub> = 125 °C <sub>chiplev.</sub>		2,1	2,55
C <sub>ies</sub>	V <sub>CE</sub> = 25, V <sub>GE</sub> = 0 V      f = 1 MHz				8,1	nF
C <sub>oes</sub>					1,2	nF
C <sub>res</sub>					1,1	nF
Q <sub>G</sub>	V <sub>GE</sub> = -8V - +20V				1200	nC
R <sub>Gint</sub>	T <sub>j</sub> = 25 °C				2,5	Ω
t <sub>d(on)</sub>	R <sub>Gon</sub> = 8 Ω		V <sub>CC</sub> = 600V I <sub>c</sub> = 100A		80	ns
t <sub>r</sub>					40	ns
E <sub>on</sub>					10	mJ
t <sub>d(off)</sub>	R <sub>Goff</sub> = 8 Ω		T <sub>j</sub> = 125 °C V <sub>GE</sub> = ±15V		460	ns
t <sub>f</sub>					65	ns
E <sub>off</sub>					9	mJ
R <sub>th(j-c)</sub>	per IGBT				0,15	K/W

# SKM 150GB128D



**SEMITRANS® 3**

## SPT IGBT Modules

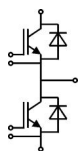
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- Electronic welders at  $f_{sw}$  up to 20 kHz



**GB**

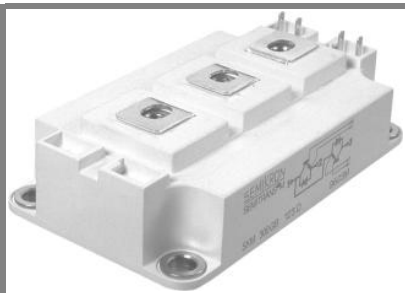
#### Characteristics

Symbol	Conditions	min.	typ.	max.	Units
<b>Inverse Diode</b>					
$V_F = V_{EC}$	$I_{Fnom} = 100 \text{ A}; V_{GE} = 0 \text{ V}$	$T_j = 25 \text{ }^\circ\text{C}_{chiplev.}$	2	2,5	V
		$T_j = 125 \text{ }^\circ\text{C}_{chiplev.}$	1,8	2,3	V
$V_{F0}$		$T_j = 25 \text{ }^\circ\text{C}$	1,1	1,45	V
		$T_j = 125 \text{ }^\circ\text{C}$		1,25	V
$r_F$		$T_j = 25 \text{ }^\circ\text{C}$	9	13	mΩ
		$T_j = 125 \text{ }^\circ\text{C}$		11	mΩ
$I_{RRM}$	$I_F = 100 \text{ A}$	$T_j = 125 \text{ }^\circ\text{C}$	145		A
$Q_{rr}$	$di/dt = 3600 \text{ A}/\mu\text{s}$		16,5		μC
$E_{rr}$	$V_{GE} = -15 \text{ V}; V_{CC} = 600 \text{ V}$		5,5		mJ
$R_{th(j-c)D}$	per diode			0,3	K/W
<b>Module</b>					
$L_{CE}$			15	20	nH
$R_{CC'+EE'}$	res., terminal-chip	$T_{case} = 25 \text{ }^\circ\text{C}$	0,35		mΩ
		$T_{case} = 125 \text{ }^\circ\text{C}$	0,5		mΩ
$R_{th(c-s)}$	per module			0,038	K/W
$M_s$	to heat sink M6		3	5	Nm
$M_t$	to terminals M6		2,5	5	Nm
w				325	g

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.

# SKM 150GB128D



SEMITRANS® 3

## SPT IGBT Modules

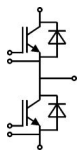
### SKM 150GB128D

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#### Typical Applications

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- UPS
- Electronic welders at  $f_{sw}$  up to 20 kHz



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$Z_{th}$			
Symbol	Conditions	Values	Units
$Z_{th(j-c)I}$			
$R_i$	$i = 1$	116	mk/W
$R_i$	$i = 2$	28	mk/W
$R_i$	$i = 3$	5,4	mk/W
$R_i$	$i = 4$	0,6	mk/W
$\tau_{ui}$	$i = 1$	0,0576	s
$\tau_{ui}$	$i = 2$	0,0073	s
$\tau_{ui}$	$i = 3$	0,023	s
$\tau_{ui}$	$i = 4$	0,02	s
$Z_{th(j-c)D}$			
$R_i$	$i = 1$	190	mk/W
$R_i$	$i = 2$	85	mk/W
$R_i$	$i = 3$	21,5	mk/W
$R_i$	$i = 4$	3,5	mk/W
$\tau_{ui}$	$i = 1$	0,0331	s
$\tau_{ui}$	$i = 2$	0,0113	s
$\tau_{ui}$	$i = 3$	0,0012	s
$\tau_{ui}$	$i = 4$	0,001	s

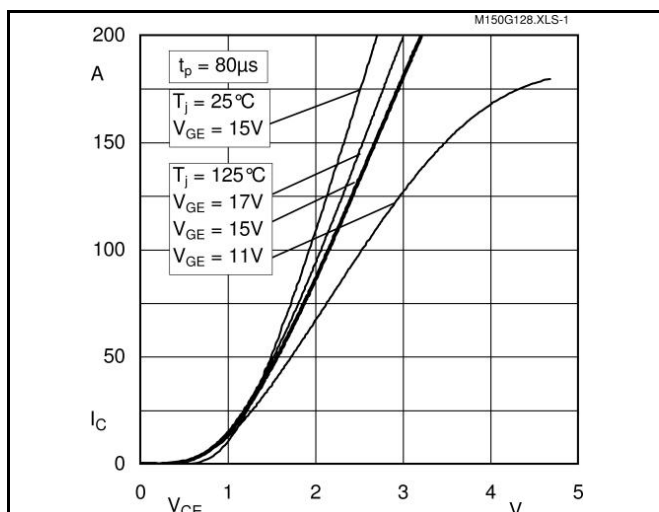


Fig. 1 Typ. output characteristic, inclusive  $R_{CC+EE'}$

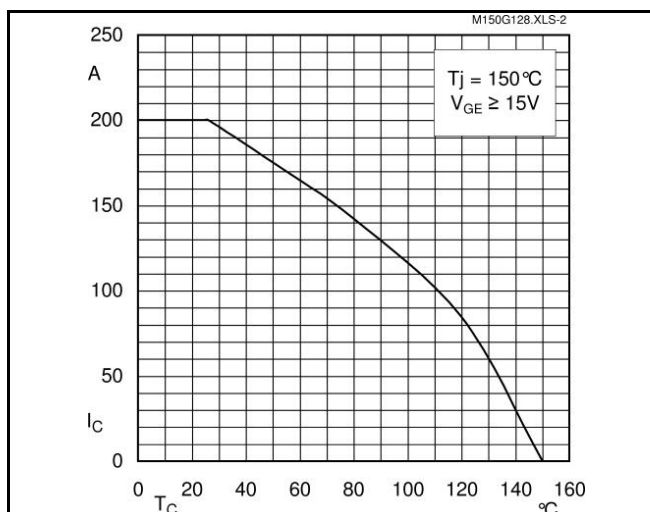


Fig. 2 Rated current vs. temperature  $I_C = f(T_C)$

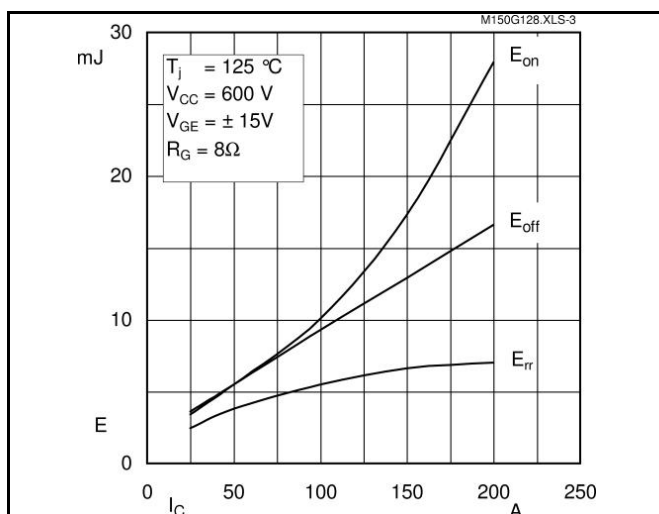


Fig. 3 Typ. turn-on /-off energy =  $f(I_C)$

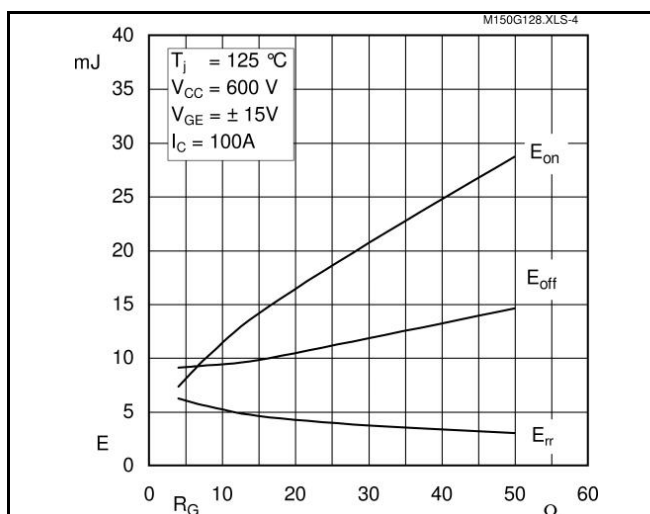


Fig. 4 Typ. turn-on /-off energy =  $f(R_G)$

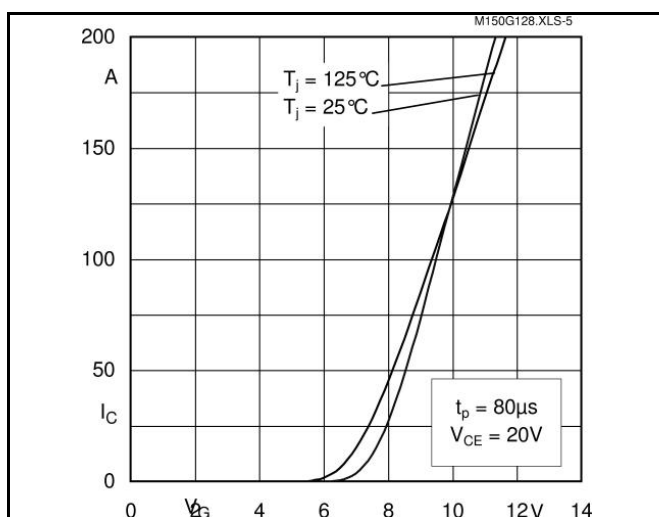


Fig. 5 Typ. transfer characteristic

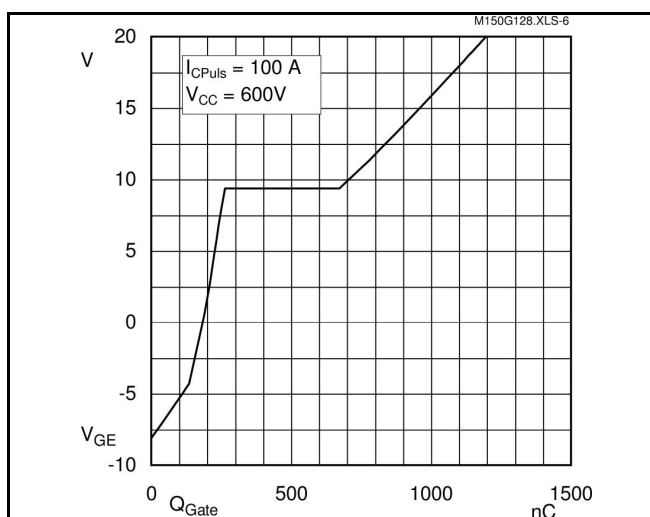
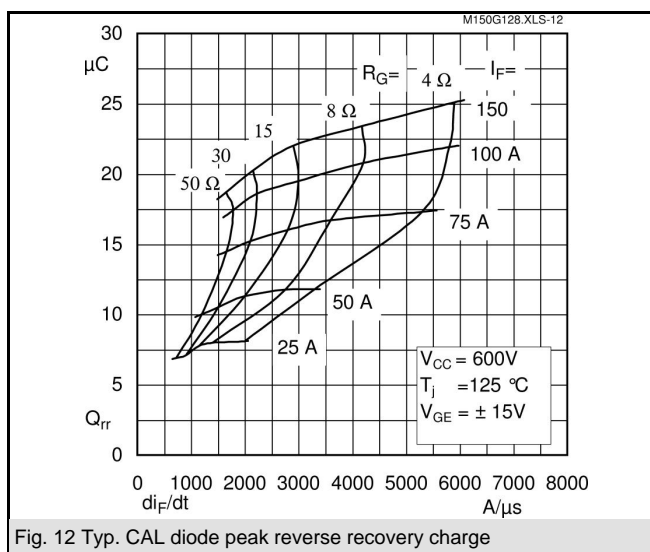
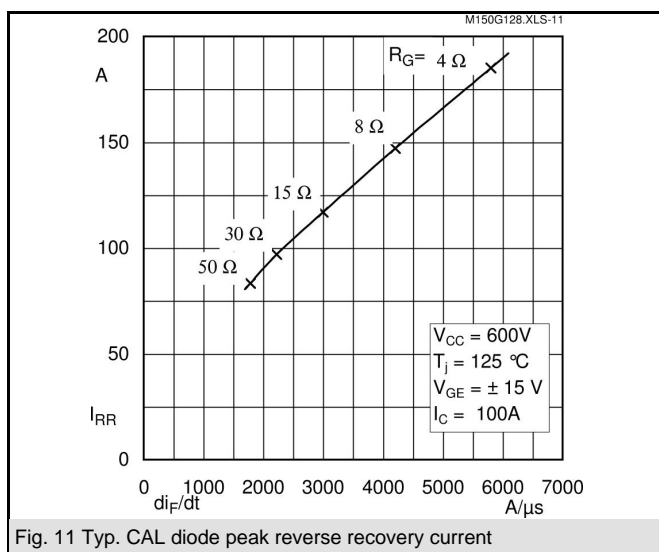
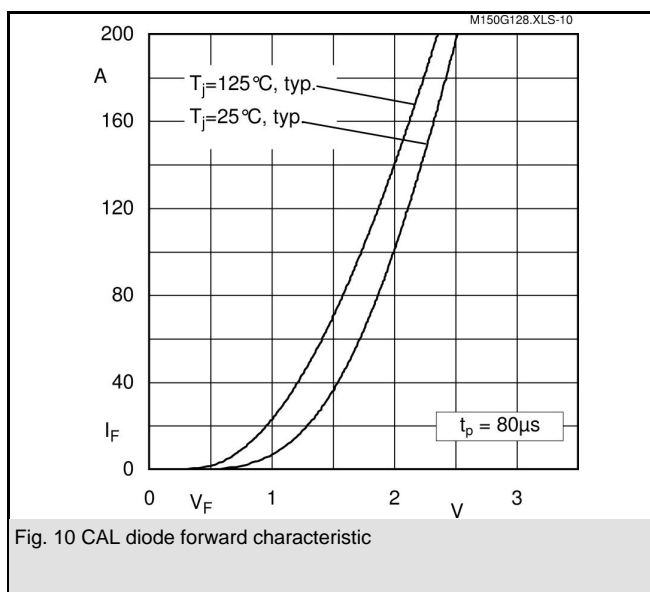
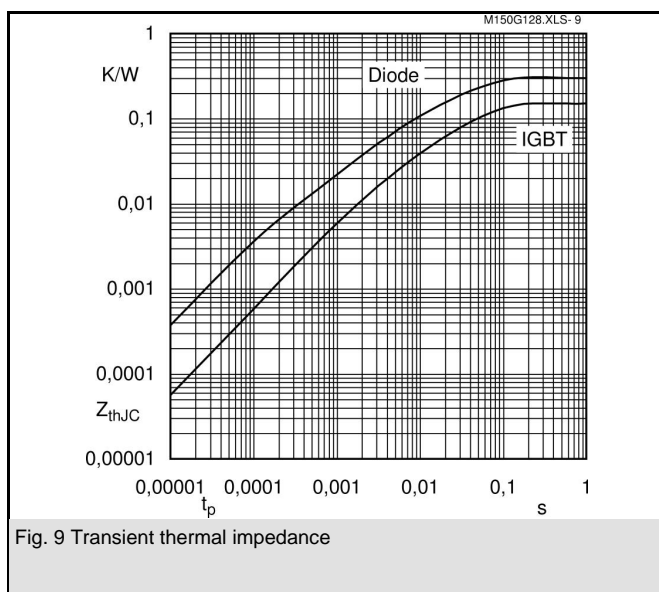
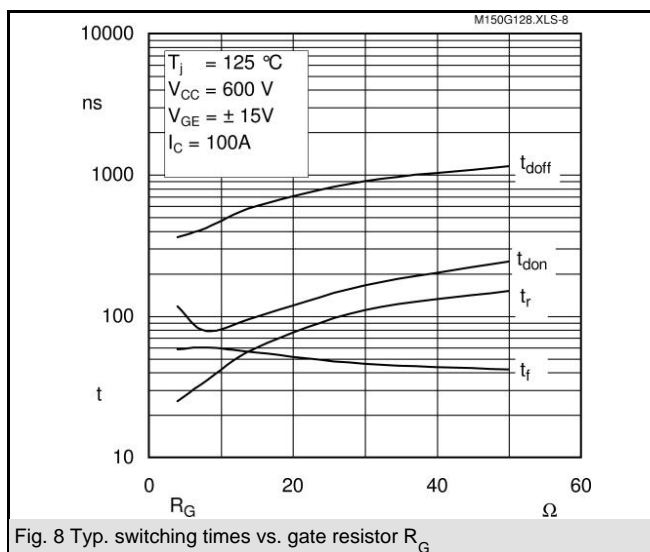
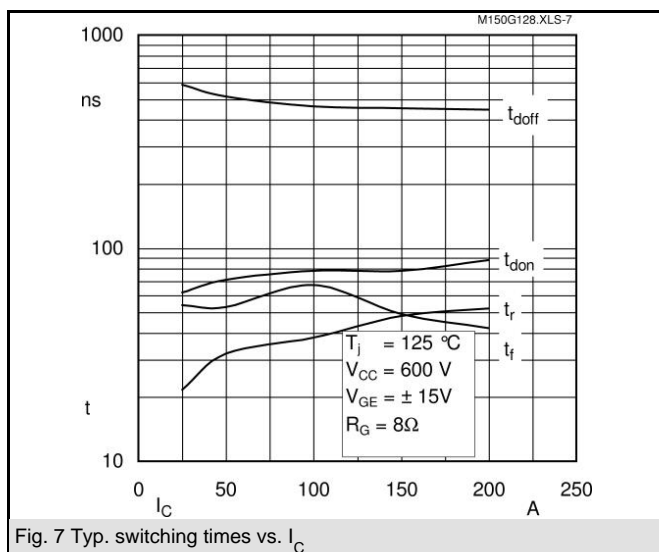
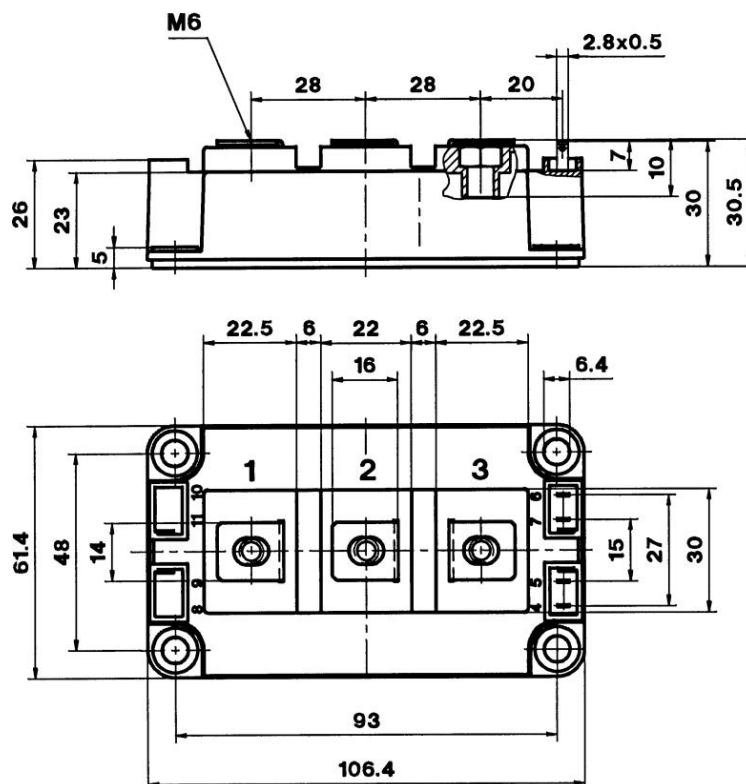


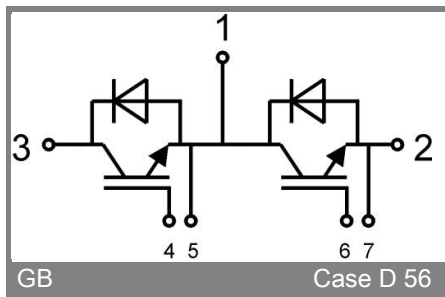
Fig. 6 Typ. gate charge characteristic



CASED56



Case D 56



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Case D 56